

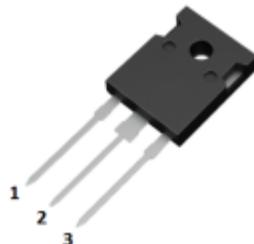


V_{RRM}	=	1200 V
$I_F (T_c \leq 135^\circ C)$	=	39 A**
Q_C	=	86 nC**

Features

- Zero Reverse Recovery Current
- Zero Forward Recovery Voltage
- Positive Temperature Coefficient on V_F
- Temperature-independent Switching
- 175°C Operating Junction Temperature
- Lead Free Package and Finish

TO-247-3



Benefits

- Replace Bipolar with Unipolar Device
- Reduction of Heat Sink Size
- Parallel Devices Without Thermal Runaway
- Essentially No Switching Losses



Applications

- Switch Mode Power Supplies
- Power Factor Correction
- Motor drive, PV Inverter, Wind Power Station

Part Number	Package	Marking
LGE3D30120D	TO-247-3	LGE3D30120D

Maximum Ratings

Symbol	Parameter	Value	Unit	Test Conditions	Note
V_{RRM}	Repetitive Peak Reverse Voltage	1200	V	$T_c = 25^\circ C$	
V_{RSM}	Surge Peak Reverse Voltage	1200	V	$T_c = 25^\circ C$	
V_R	DC Blocking Voltage	1200	V	$T_c = 25^\circ C$	
I_F	Forward Current (Per leg/Device)	42/84 19.5/39 15/30	A	$T_c \leq 25^\circ C$ $T_c \leq 135^\circ C$ $T_c \leq 150^\circ C$	
I_{FSM}	Non-Repetitive Forward Surge Current	137*	A	$T_c = 25^\circ C, t_p = 8.3ms$, Half Sine Wave	
P_{tot}	Power Dissipation (Per leg/Device)	214/ 428	W	$T_c = 25^\circ C$	Fig.3
T_c	Maximum Case Temperature	150	°C		
T_J, T_{STG}	Operating Junction and Storage Temperature	-55 to 175	°C		
	TO-247 Mounting Torque	1	Nm	M3 Screw	

*Per Leg, **Per Device

Electrical Characteristics (Per Leg)

Symbol	Parameter	Typ.	Max.	Unit	Test Conditions	Note
V_F	Forward Voltage	1.55 2.2	1.8 2.5	V	$I_F = 15A, T_J = 25^\circ C$ $I_F = 15A, T_J = 175^\circ C$	Fig.1
I_R	Reverse Current	5 20	20 200	μA	$V_R = 1200V, T_J = 25^\circ C$ $V_R = 1200V, T_J = 175^\circ C$	Fig.2
C	Total Capacitance	940 70 57	/	pF	$V_R = 0V, T_J = 25^\circ C, f = 1MHz$ $V_R = 400V, T_J = 25^\circ C, f = 1MHz$ $V_R = 800V, T_J = 25^\circ C, f = 1MHz$	Fig.5
Q_C	Total Capacitive Charge	43	/	nC	$V_R = 800V, I_F = 15A$ $di/dt = 200A/\mu s, T_J = 25^\circ C$	Fig.4

Thermal Characteristics

Symbol	Parameter	Typ.	Unit	Note
$R_{\theta JC}$	Thermal Resistance from Junction to Case	0.7* 0.35**	°C/W	Fig.6
$R_{\theta JA}$	Thermal Resistance from Junction to Ambient	80	°C/W	
T_{sold}	Soldering Temperature	260	°C	

*Per Leg, **Per Device

Typical Performance

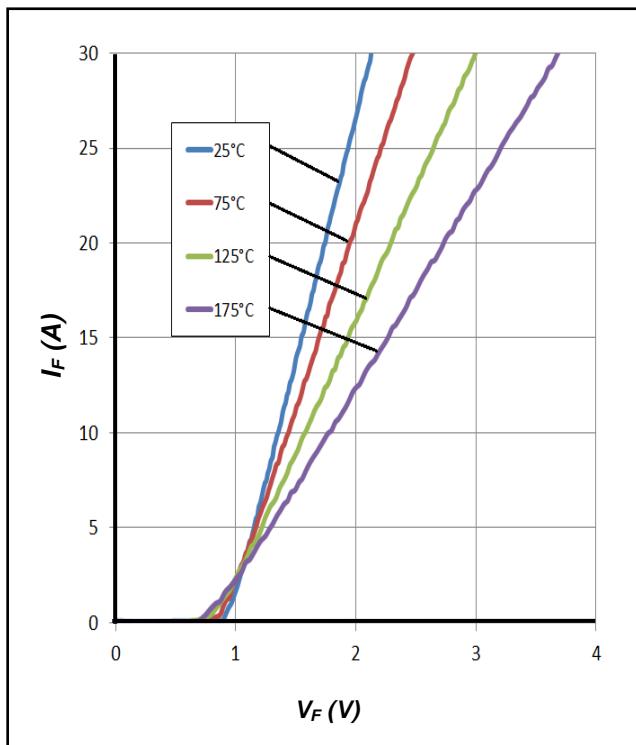


Figure 1. Forward Characteristics

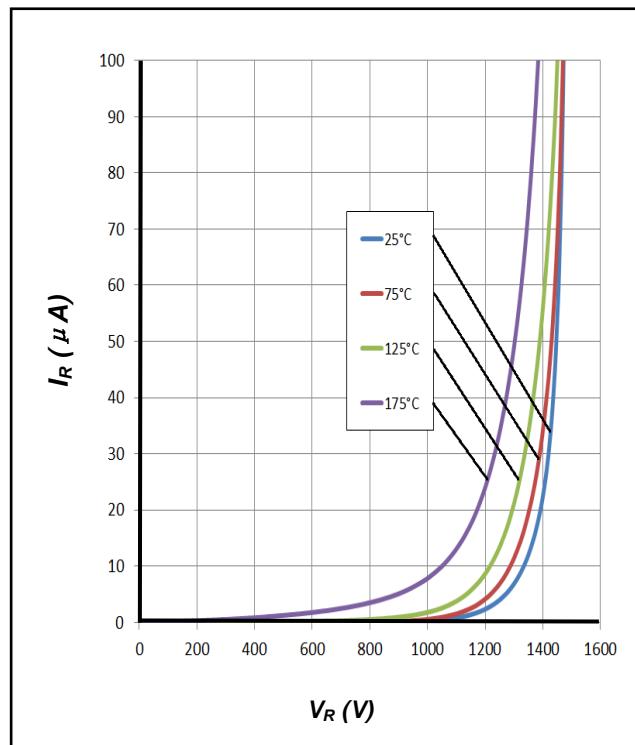


Figure 2. Reverse Characteristics

Typical Performance

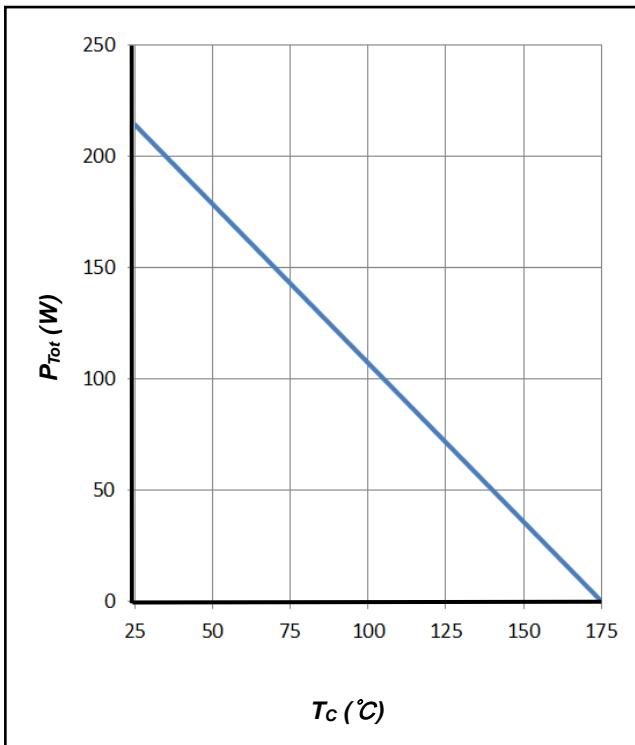


Figure 3. Power Derating

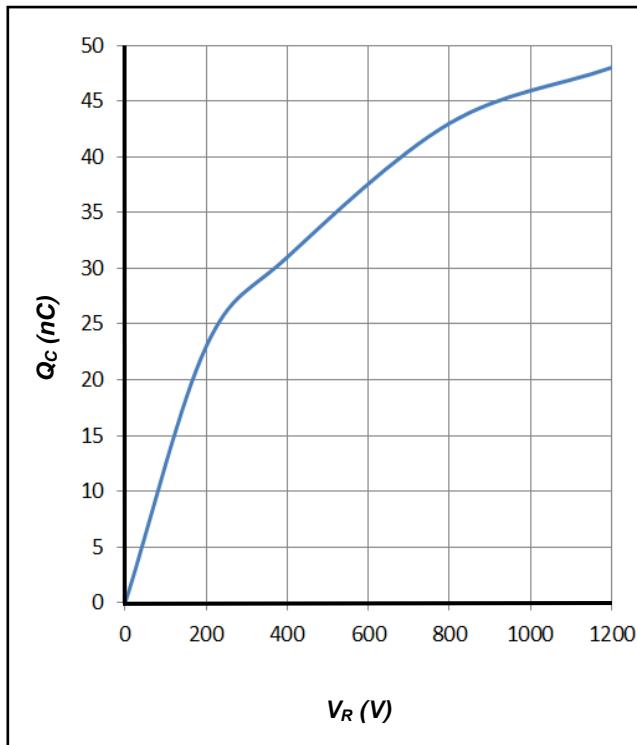


Figure 4. Total Capacitive Charge vs. Reverse Voltage

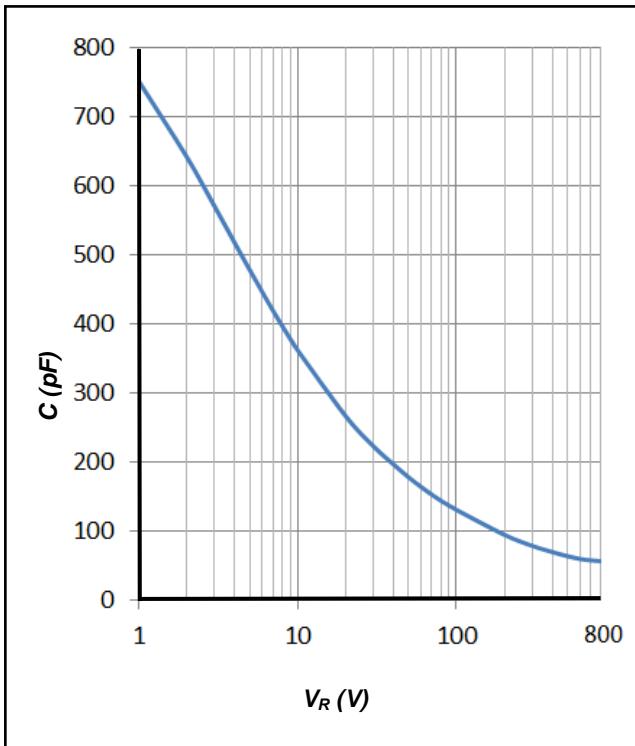


Figure 5. Total Capacitance vs. Reverse Voltage

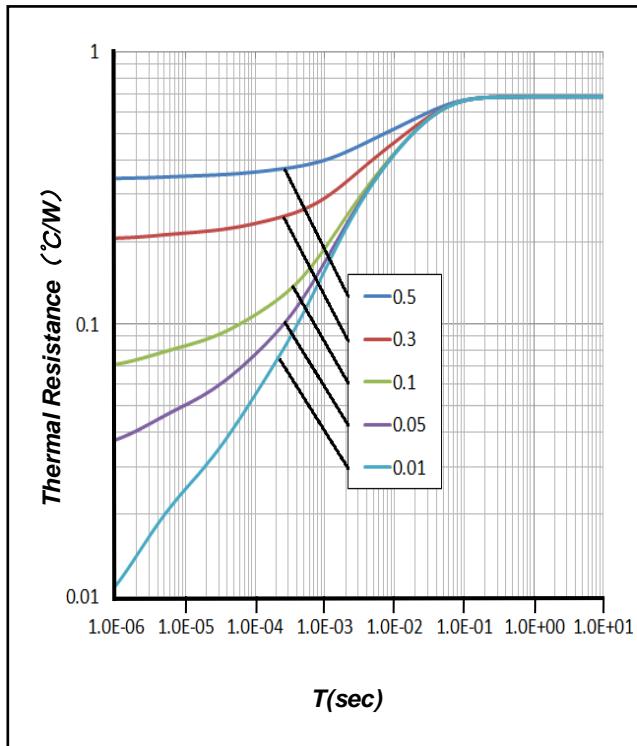
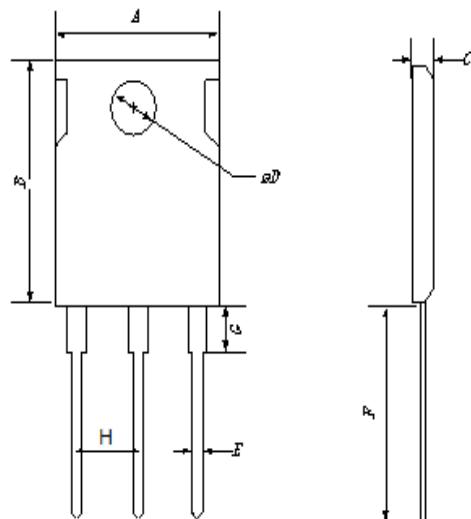


Figure 6. Transient Thermal Impedance



Package Dimensions

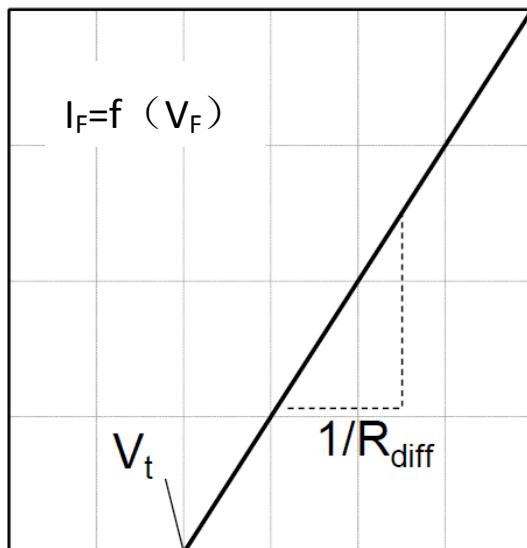
Package TO-247-3



Symbol	Min. (mm)	Typ. (mm)	Max. (mm)
A	14.18	15.75	17.33
B	18.45	20.5	22.55
C	4.50	5.00	5.50
D	3.15	3.50	3.85
E	1.08	1.20	1.32
F	18.27	20.30	22.33
G	4.21	4.68	5.15
H	4.91	5.46	6.01

Simplified Diode Model

Equivalent IV Curve for Model



Mathematical Equation(Per Leg)

$$V_F = V_t + I_F \times R_{\text{diff}}$$

$$V_t = -0.001 \times T_j + 0.9836 \quad [\text{V}]$$

$$R_{\text{diff}} = 1 \times 10^{-6} \times T_j^2 + 1 \times 10^{-4} \times T_j + 0.0347 \quad [\Omega]$$

Note:

T_j = Diode Junction Temperature In Degrees Celsius,
valid from 25°C to 175°C

I_F = Forward Current
Less than 30A

Packge	Packing	Box Size LxWxH(mm)	Quatity(pcs/box)	Carton Size LxWxH(mm)	Quatity(pcs/carton)
TO-247	30pcs/Tube	570×155×50	450	580×340×125	1800